

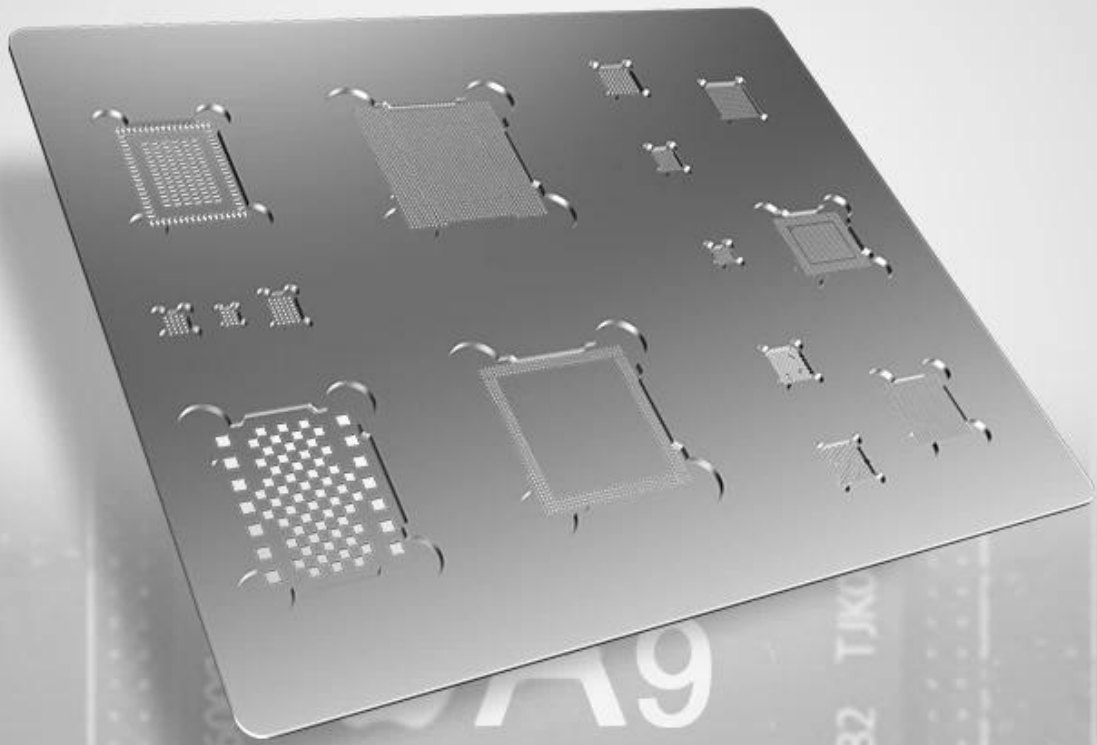
BEST-A9-High Quality Universal BGA IC Chip Stencils Heated Template Reballing Stencil for iphone 6 6P

1x BGA Reballing Stencils for iPhone 6s Plus

1x BGA Reballing Stencils for iPhone 6s

3D GROOVE

— REBALLING STENCIL —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

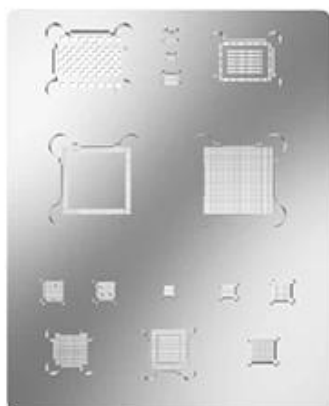


PRECISE ALIGNMENT



SQUARE HOLE

Product Usage



MODEL	A9
WEIGHT	18.8g
MATERIAL	imported steel
SIZE	68.9 X 84.9mm
MATCHING MACHINE TYPE	iPhone6S/6SPlus

▼ CHARACTERISTICS

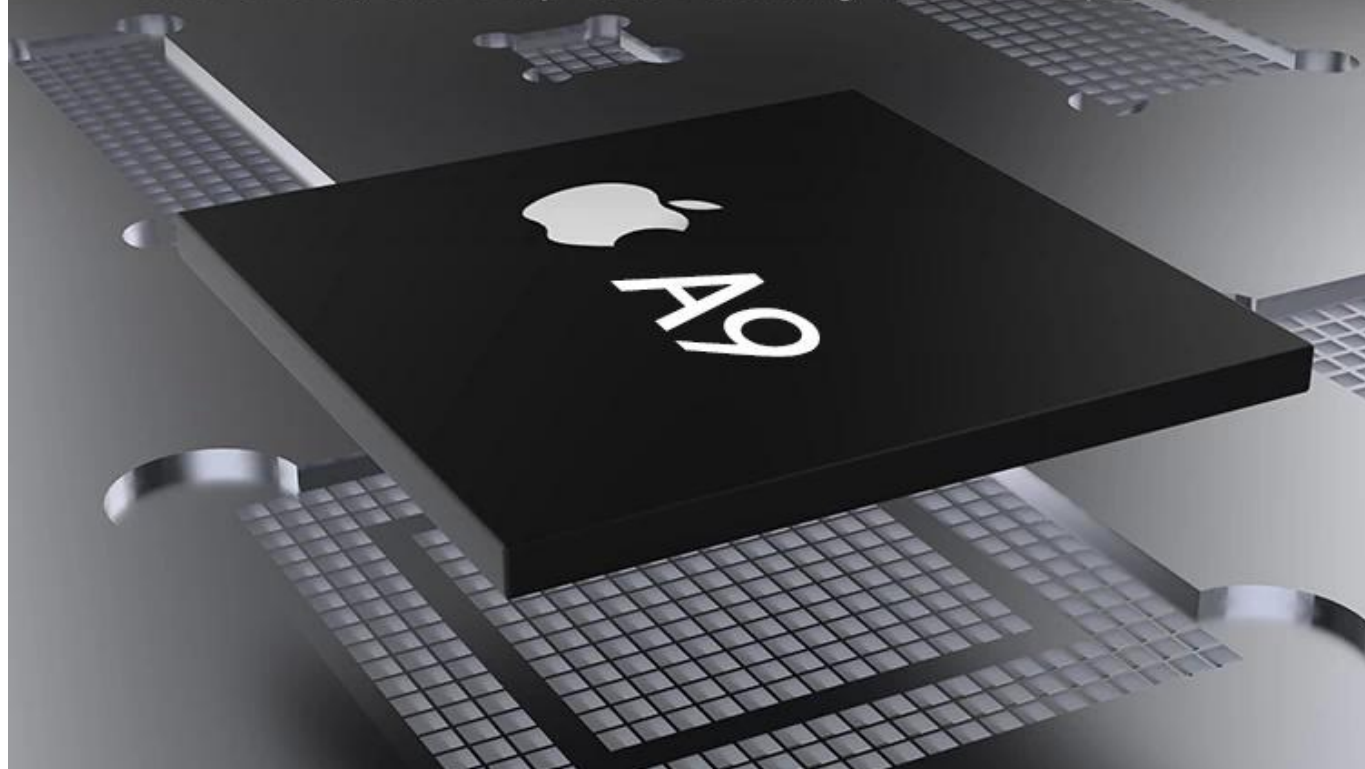
This product is used for BGA tinning repair of the iPhone 6S/6sPlus series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

IMPORTED STEEL

HIGH TOUGHNESS

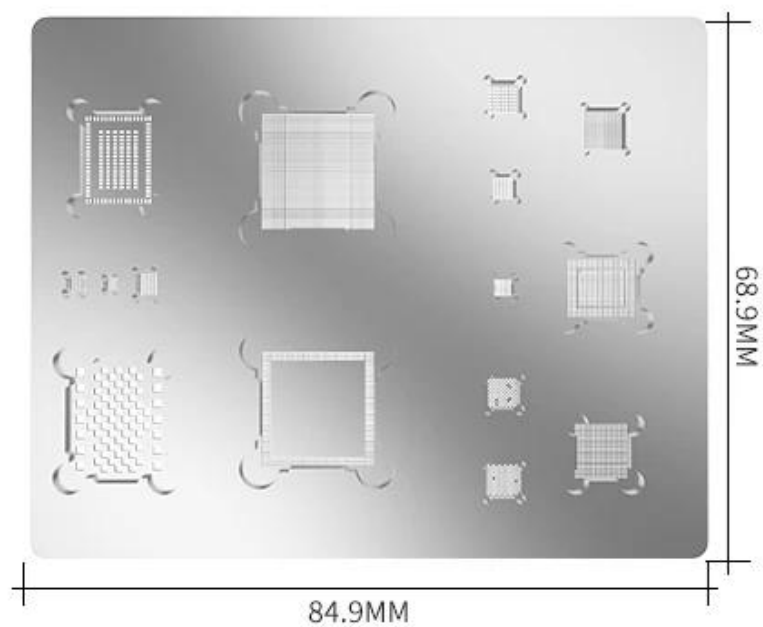


Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"





PRODUCT SIZE



Thin to 0.31mm

Precise die-casting **form heating**



